MIRTEC to Present Complete Line of Advanced 3D AOI and SPI Inspection Systems in Exclusive ONLINE CONFERENCE & EXPO

June 2020 – MIRTEC, ‘The Global Leader in Inspection Technology,’ is excited to announce its participation in an exclusive ONLINE CONFERENCE & EXPO. The event will be broadcast live on Wednesday, July 8, 2020 from 10 a.m. - 2:30 p.m. EST and will include a full program of live presentations, interviews and special guests.

Sponsored by Global SMT & Packaging, the ONLINE CONFERENCE & EXPO will feature the latest technical presentations, video booth interviews and new products from eight exhibitors. To learn more or to register as a visitor, visit https://app.greenrope.com/users/myteam45084/Media653.html.

“We are looking forward to participating in this exclusive ONLINE EXPO,” stated Brian D’Amico, President of MIRTEC’s North American Sales and Service Division. “MIRTEC will feature video feed and information about our award-winning inspection solutions specifically designed to address the full spectrum of inspection requirements associated with the Electronics Manufacturing Industry.”

The MV-6 OMNI 3D AOI Machine is configured with MIRTEC’s exclusive OMNI-VISION® 3D Inspection Technology which combines our 15 Mega Pixel CoaXPress Camera Technology with MIRTEC’s revolutionary Digital Tri-Frequency Moiré 3D system in a cost-effective platform. MIRTEC’s 15 Mega Pixel CoaXPress Vision System is a proprietary camera system designed and manufactured by MIRTEC for use with our complete product range of 3D inspection systems. MIRTEC’s Digital Tri-Frequency Moiré Technology, provides true 3D inspection using a total of four (4) Programmable Digital Moiré Projectors to yield precise height measurement data used to detect lifted component and lifted lead defects as well as solder volume post reflow. Fully configured the MIRTEC MV-6 OMNI machines feature four (4) 10 Mega Pixel Side-View Cameras in addition to the 15 Mega Pixel Top-Down Camera. There is little doubt that this new technology has set the standard by which all other inspection equipment is measured.

MIRTEC’s MV-3 OMNI Desktop 3D AOI Machine is configured with the same hardware and software as MIRTEC’s in-line OMNI-VISION® 3D Inspection Systems providing 100 percent compatibility across MIRTEC’s entire 3D AOI product line. These systems feature MIRTEC’s exclusive OMNI-VISION® 3D Inspection Technology which combines our 15 Mega Pixel CoaXPress Camera Technology with MIRTEC’s revolutionary Digital Tri-Frequency Quad Moiré 3D system in a newly designed desktop platform. MIRTEC’s 15 Mega Pixel CoaXPress Vision System is a proprietary camera system designed and manufactured by MIRTEC for use with our complete product range of 3D inspection systems. MIRTEC’s Digital Multi-Frequency Quad Moiré Technology, provides true 3D inspection using a total of four (4) Programmable Digital Moiré Projectors to yield precise height measurement data used to detect lifted component and lifted lead defects as well as solder volume post reflow. Fully configured the new MIRTEC MV-3 OMNI machine features four (4) 10 Mega Pixel Side-View Cameras in addition to the 15 Mega Pixel CoaXPress Top-Down Camera. Without question, the MV-3 OMNI is the most Technologically Advanced Desktop 3D AOI machine in the world!
MIRTEC’s MS-11e 3D SPI Machine is configured with an exclusive 15 Mega Pixel CoaXPress Camera System, providing enhanced image quality, superior accuracy and incredibly fast inspection rates.

The MS-11e uses Dual Projection Shadow Free Moiré Phase Shift Imaging, excessive Technology to inspect solder paste depositions on PCBs post screen print for insufficient solder, shape deformity, shift of deposition and bridging. The MS-11e uses the same robust platform as MIRTEC’s MV-6 OMNI Series.

Smart Inspection Software using AI based on Deep Learning Methodology

MIRTEC’s Automatic Programming Software uses Artificial intelligence based Deep Learning Methodology to minimize human error and standardize the programming process. This advanced software solution automatically analyzes the PCB architecture and assigns the appropriate part type and process parameters for each SMT device thereby maximizing programming efficiency. Only basic operator training is required to achieve optimal inspection results.

MIRTEC’s ‘Best-in-Class’ Optical Character Recognition (OCR) Technology reduces false calls and improves production process efficiency by automatically restoring and inspecting damaged characters through AI and Deep Learning.

Leading the Way to Industry 4.0

MIRTEC’s Total Remote Management System (TRMS) is a fully integrated Industry 4.0 Solution which combines remote management with real-time data monitoring and analysis for each system within the SMT production line. MIRTEC’s TRMS provides real-time remote monitoring of status information and statistical data such as; equipment operation status, production yield, PC resources, temperature, humidity, etc.

The combination of MIRTEC’s 3D AOI and TRMS systems provide a vast improvement in production process management over common AOI technologies and management software. The TRMS Module is a key part of MIRTEC’s Intelligent Factory Automation System, INTELLISYS®. This powerful software suite was designed and developed by MIRTEC to provide manufacturers with a clear view into the manufacturing process, thereby helping them achieve higher operating efficiencies and improved quality.

“MIRTEC continues to set new standards within the highly competitive Electronics Inspection Industry’, continued D’Amico. “These revolutionary products provide unprecedented 3D inspection performance and the industry’s lowest cost of ownership making them an ideal solution for electronics manufacturing companies of all sizes. We look forward to welcoming visitors to our booth #1900 during the three-day event.”

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MIRTEC is a leading global supplier of automated inspection systems to the electronics manufacturing industry. For further information, please visit [www.mirtec.com](http://www.mirtec.com)